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FORM PTO-1595 1-31-92 100965309

HEET

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office Docket No.:KN-21-US

.ached original documents or copy thereof.

2.4.99

To the Honorable Commissioner of

(0.10)	
Name of conveying party(les):	Name and address of receiving party(ies):
Rieka Ohuchi	1/
Takatoshi Suzuki	Name: NEC CORPORATION
Additional names of conveying party(ies) attached	//Internal Address:
□ yes ☑ no	Street Address: 7-1, Shiba 5-chome, Minato-ku,
TAD CANAL	City: Tokyo
3. Nature of Conveyance	Country: Japan
☑ Assignment ☐ Merger	
☐ Security Agreement ☐ Change of Name	Additional name(s) & address(es) attached? ☐ yes ☑ no
□ Other Execution Date: January 11, 1999	
Execution Date: Samuary 11, 1999	
Application number(s) or patent number(s): Title: SEMICONDUCTOR DEVICE WITH HIGH RELIABILITY OF SEMICONDUCTOR ELEMENT AND CONDUCTIVE WIRE OF SIf this document is being filed together with a new application, the exe	SUBSTRATE AND METHOD OF MANUFACTURING THE SAME
A. Patent Application No(s). 09/179,557 filed on October 27, 1998	B. Patent No(s).
Additional numbers atta	ched? □ Yes ☑ No
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:1_
C. Lamont Whitham	7. Total fee (37 CFR 3.41): \$.40.00
Whitham, Curtis & Whitham	☑ Enclosed
Reston International Center	☑ Authorized to be charged to deposit account
11800 Sunrise Valley Drive Suite 900	☐ Total fee due
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Statement and signature	
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To the hest of my knowledge and helief, the foregoing information is true	and contest and any addenied copy is a due copy of the oliginal
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document. Andrew M. Calderon	2/4/99
document.	Zન્નેપ્વ Date Total number of pages including cover sheet:

PATENT REEL: 9753 FRAME: 0345 PATENT OR DESIGN: SOLE OR JOINT

(U.S. and Foreign Rights)

ASSIGNMENT FOR UNFILED APPLICATION FOR UNITED STATES PATENT

(Sole or Joint Inventors)

WHEREAS:

RIEKA OHUCHI, TAKATOSHI SUZUKI c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan

POST OFFICE ADDRESS(S)
OF INVENTOR(S) (including country)

FULL NAME(S) AND

(hereinafter referred to as ASSIGNOR), have invented and own a certain invention entitled:

TITLE OF INVENTION

SEMICONDUCTOR DEVICE WITH HIGH RELIABILITY OF CONNECTION BETWEEN PROJECTIVE ELECTRODE OF SEMICONDUCTOR ELEMENT AND CONDUCTIVE WIRE OF SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

for which application for Letters Patent of the United States has been executed on even date herewith.

FULL NAME AND
ADDRESS (including country)
OF ASSIGNEE

WHEREAS: NEC Corporation 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan

(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention and in, to and under Letters Patent or similar legal protection to be obtained therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by AS-SIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, division, renewal, substitute or reissue thereof or

(Assignment for Unfiled Application for United States Patent—page 1 of 2)

PATENT REEL: 9753 FRAME: 0346 any legal equivalent thereof in a foreign country for the full term or terms for which the same may be granted.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof in any foreign country which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/We have hereunto set hand 11th day of January,

(Date of Signing)

and seal this

(Signature)

(Signature)

(Signature)

Witness:

All information, names of inventor(s) and assignee, title of invention and particulars of application should be completed.

No witnessing or legalization is necessary. However, if this assignment is legalized then it will only be prime facie evidence of the execution of the assignment.

(Assignment for Unfiled Application for United States Patent—page 2 of 2)

Instruction sheet for assignment Signing

RECORDED: 02/04/1999

Warning

This must be the same as the

correspond with the name(s) of

date of signing of the declaration and power of the patent

DATE OF SIGNING:

or design application.

the inventor(s) above.

SIGNATURE(S) The signature(s) must

> PATENT REEL: 9753 FRAME: 0347